

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A positive photosensitive resin composition,  
comprising:

an alkali-soluble resin, a 1,2-quinone diazide compound, a crosslinking compound  
having at least two epoxy groups and a surfactant,

wherein the ~~above~~ alkali-soluble resin is a copolymer comprising copolymerized units  
of a carboxyl group-containing acrylic monomer, a hydroxyl group-containing acrylic  
monomer and an N-substituted maleimide as essential components.

Claim 2 (Original): The positive photosensitive resin composition according to  
Claim 1, which comprises the 1,2-quinone diazide compound in an amount of from 5 to 100  
parts by weight, the crosslinking compound having at least two epoxy groups in an amount of  
from 1 to 50 parts by weight, and the surfactant in an amount of from 0.01 to 2 parts by  
weight, based on 100 parts by weight of the alkali-soluble resin component.

Claim 3 (Currently Amended): The positive photosensitive resin composition  
according to Claim 1 ~~or 2~~, wherein the number average molecular weight of the copolymer is  
from 2,000 to 9,000.

Claim 4 (Currently Amended): The positive photosensitive resin composition  
according to ~~any one of 1 to 3~~ Claim 1, wherein the copolymer comprises copolymerized  
units of the carboxyl group-containing acrylic monomer in an amount of from 5 to 30 mol%,

the hydroxyl group-containing acrylic monomer in an amount of from 5 to 50 mol% and the N-substituted maleimide in an amount of from 10 to 70 mol% ~~as monomer components~~.

Claim 5 (Currently Amended): The positive photosensitive resin composition according to ~~any one of Claims 1 to 4~~ Claim 1, wherein the surfactant is a ~~fluorine type~~ fluorine-containing surfactant.

Claim 6 (Canceled).

Claim 7 (New): The positive photosensitive resin composition according to Claim 1, wherein the alkali-soluble resin comprises copolymerized units of at least one carboxyl group-containing acrylic monomer selected from the group consisting of acrylic acid and methacrylic acid.

Claim 8 (New): The positive photosensitive resin composition according to Claim 1, wherein the alkali-soluble resin comprises the carboxyl group-containing acrylic monomer in an amount of from 5 to 20 mol%, the hydroxyl group-containing acrylic monomer in an amount of from 20 to 30 mol%, and the N-substituted maleimide in an amount of from 20 to 40 mol%.

Claim 9 (New): The positive photosensitive resin composition according to Claim 1, wherein the hydroxyl group-containing acrylic monomer is at least one selected from the group consisting of a 2-hydroxyethyl acrylate, 2-hydroxypropyl acrylate, 2-hydroxyethyl methacrylate and 2-hydroxypropyl methacrylate.

Claim 10 (New): The positive photosensitive resin composition according to Claim 1, wherein the N-substituted maleimide is at least one selected from the group consisting of cyclohexylmaleimide, phenylmaleimide, methylmaleimide and ethylmaleimide.

Claim 11 (New): The positive photosensitive resin composition according to Claim 1, wherein the alkali-soluble resin composition comprises copolymerized units of the carboxyl group-containing acrylic monomer in an amount of from 5 to 20 mol%, the hydroxyl group-containing acrylic monomer in an amount of from 20 to 30 mol%, and the N-substituted maleimide in an amount of from 20 to 40 mol%, and further comprises copolymerized units of one or more other acrylic monomers in an amount of from 10 to 55 mol%.

Claim 12 (New): The positive photosensitive resin composition according to Claim 1, wherein the 1,2-quinone diazide has hydroxyl groups, amino groups or both hydroxyl groups and amino groups, that are esterified or amidated with 1,2-quinone diazide sulfonic acid.

Claim 13 (New): The positive photosensitive resin composition according to Claim 1, wherein the 1,2-quinone diazide compound is 4,4'-[1-[4-[1-(4-hydroxyphenyl)-1-methylethyl]phenyl]ethylidene]bisphenol esterified with 1,2-quinone diazide sulfonic acid.

Claim 14 (New): The positive photosensitive resin composition according to Claim 1, wherein the crosslinking compound is an epoxy resin having a cyclohexene oxide structure.

Claim 15 (New): The positive photosensitive resin composition according to Claim 1, further comprising a silane adhesion promoter.

Claim 16 (New): The positive photosensitive resin composition according to Claim 1, wherein the alkali-soluble resin comprises co-polymerized monomer units of methacrylic acid, N-cyclohexyl maleimide, hydroxyethyl methacrylate and methyl methacrylate; the 1,2-quinone diazide compound is produced by condensation of 4,4'-[1-[4-[1-(4-hydroxyphenyl)-1-methylethyl]phenyl]ethylidene]bisphenol with 1,2-naphthoquinone-2-diazide-5-sulfonyl chloride; the crosslinking compound has a cyclohexene oxide structure with four functional groups.

Claim 17 (New): A method, comprising:  
applying the positive photosensitive resin composition according to Claim 1 onto a substrate, then  
imagewise exposing the substrate,  
forming a first pattern, and  
postbaking to form a second pattern having a semicircular or trapezoidal section.

Claim 18 (New): The method of Claim 17, wherein the imagewise exposing and the forming include pre-drying the substrate after the applying, irradiating with light through a mask having a pattern mounted thereon, and developing with an alkaline developer, and  
wherein the postbaking is carried out after the imagewise exposing and the forming.

Claim 19 (New): The method of Claim 17, wherein the imagewise exposing and the forming include prebaking the substrate after the applying, irradiating the prebaked substrate with ultraviolet rays, then developing with an aqueous solution, then washing with water, and then irradiating with ultraviolet rays; and

wherein the postbaking is carried out after the imagewise exposing and the forming.